Docket No.: JCLA26302

RECORDATION FORM	Patent and Trademark Office
PATENTS OF	NLY
To the Director of the U.S. Patent and Trademark Office: Pleas	e record the attached documents or the new address(es) below
Name of conveying party(ies) with the execution date:	2. Name/address of receiving Party(ies)
XIAOSHAN CHEN, September 09, 2008	VIA TECHNOLOGIES, INC. 8F, NO. 533, CHUNG-CHENG RD., HSIN-TIEN CITY, TAIPEI HSIEN, TAIWAN, R.O.C.
3. Nature of conveyance:	CITY, TAIPEL ASIEN, TAIVVAN, R.O.C.
Assignment	Add'1 names of receiving parties Attached? Yes X No
4. Application number(s) or patent number(s)	
A. Patent Application No. (s) 12/207,676	B. Patent No.(s)
Additional number attached? 5. Name and address of party to whom correspondence concerning document should be mailed:	Yes x No 6. Total No. of applications and patents involved: ONE (1) 7. Total fee(37CFR§3.41): \$ 40.00
J. C. Patents 4 Venture, Suite 250 Irvine, CA 92618 (949) 660-0761	Authorized to be charged by credit card X Authorized to be charge to deposit account Enclosed None required (government interest not affecting title) 8. Payment Information a. Credit Card Last 4 Numbers Expiration Date
Atty Docket No.: JCLA26302 9. Statement and Signature:	b. Deposit Account Number <u>50-0710</u> Authorized User Name <u>Jiawei Huang</u>
To the best of my knowledge and be Correct and any attached copy is a	lief, the forging information is true and true copy of the original document.
Jiawei Huang Name of person Signing Registration No. 43,330 Signature	Date Total number of pages including cover sheet, attachments, and documents: 3

PATENT

REEL: 021513 FRAME: 0360

S3U07-0015 26302-US-PA

ASSIGNMENT

WHEREAS,

1. Chen, Xiaoshan

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: ROUTING STRUCTURE OF RE-DISTRIBUTION LAYER AND METHOD FOR RE-DISTRIBUTING ROUTING STRUCTURE IN INTEGRATED CIRCUIT

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, VIA Technologies, Inc.

of 8F, No. 535, Chung-Cheng Rd., Hsin-Tien City, Taipei Hsien, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

S3U07-0015100-US

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: <u>Liaoshan Chen</u> Date: Sep. 9, 2008
Sole or First Joint Inventor. XIAOSHAN CHEN

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